LNJ107W5PRW

Surface Mounting Chip LED

S-GW-2 Type

■ Absolute Maximum Ratings $T_a = 25$ °C

• Yellow Green

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	60	mW	
Forward current	I_{F}	20	mA	
Pulse forward current *	I_{FP}	60	mA	
Reverse voltage	V _R	4	V	
Operating ambient temperature	T _{opr}	-25 to +85	°C	
Storage temperature	T _{stg}	-30 to +100	°C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

• Red

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	60	mW	
Forward current	I_{F}	20	mA	
Pulse forward current *	I_{FP}	60	mA	
Reverse voltage	V _R	3	V	
Operating ambient temperature	T _{opr}	-25 to +85	°C	
Storage temperature	T _{stg}	-30 to +100	°C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25$ °C

• Yellow Green

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O	$I_F = 10 \text{ mA}$	3.0	5.0		mcd
Reverse current	I_R	$V_R = 4 V$			10	μΑ
Forward voltage	V _F	$I_F = 10 \text{ mA}$		2.03	2.6	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 10 \text{ mA}$		565		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		30		nm

■ Lighting Color

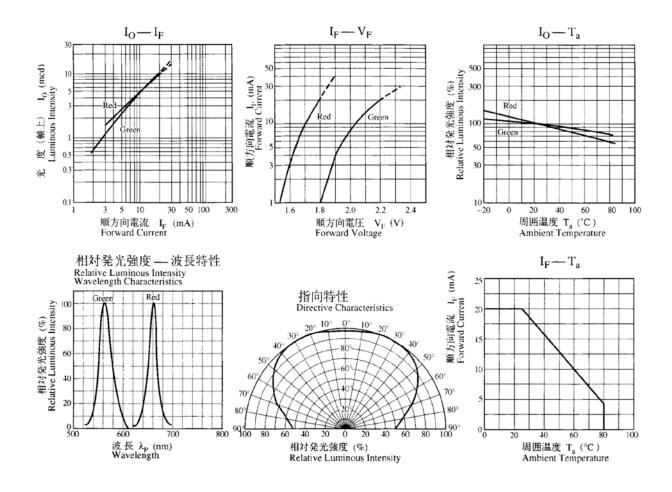
- Yellow Green
- Red

LNJ107W5PRW Panasonic

■ Electro-Optical Characteristics (Continued) $T_a = 25$ °C

• Red

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O	$I_F = 10 \text{ mA}$	1.7	5.0		mcd
Reverse current	I_R	$V_R = 3 V$			100	μΑ
Forward voltage	V_{F}	$I_F = 10 \text{ mA}$		1.72	2.5	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 10 \text{ mA}$		660		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		20		nm

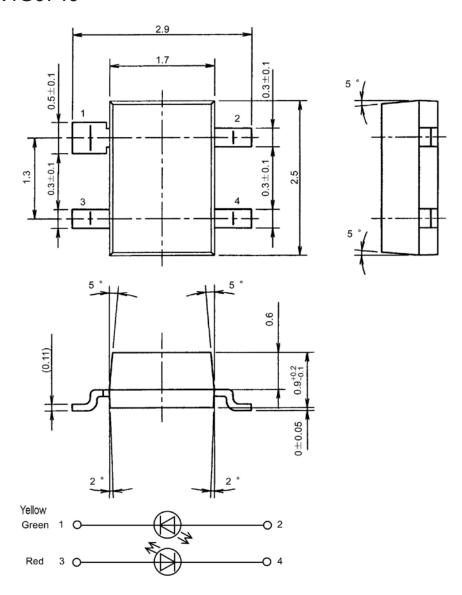


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Panasonic LNJ107W5PRW

■ Package (Unit: mm)

LLTFTN4G0740



- Pin name
 - 1, 4: Cathode
 - 2, 3: Anode

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